

In the Claims

1.-22. (Cancelled)

23. (Currently Amended) An adhesion-enhanced polyimide film which comprises a core layer composed of a polyimide (A) having high rigidity and a low linear expansion coefficient, at least one side of which has a thin-layer with a thickness of 0.05 to 1  $\mu\text{m}$  formed by heating a coated layer comprising a heat-resistant surface treatment agent ~~comprising an aminosilane compound, an epoxysilane compound or a titanate compound, selected from N-[ $\beta$ -(phenylamino)-ethyl]- $\gamma$ -aminopropyl-triethoxysilane, N-phenyl- $\gamma$ -aminopropyl-triethoxysilane and  $\gamma$ -phenylaminopropyl-triethoxysilane~~ and a polyimide precursor which yields a highly heat-resistant amorphous polyimide (B) obtained from two components consisting of i) at least one aromatic tetracarboxylic dianhydride selected from the group consisting of 2,3,3',4'-biphenyltetracarboxylic dianhydride and 2,2',3,3'-biphenyltetracarboxylic dianhydride and ii) at least one aromatic diamine selected from the group consisting of p-phenylenediamine and 4,4'-diaminodiphenyl ether, which is obtained by heating at a maximum heating temperature of 370-575°C a multilayer self-supporting film obtained by coating an organic solvent solution comprising the heat-resistant surface treatment agent and the polyimide precursor which yields a highly heat-resistant amorphous polyimide (B) onto at least one side of a self-supporting film obtained from a polyimide precursor solution which yields the polyimide (A) core layer, wherein the polyimide film as a whole has a tensile modulus (MD) of between 6 GPa and 12 GPa and a linear expansion coefficient of  $5 \times 10^{-6}$  to  $30 \times 10^{-6}$  cm/cm/ $^{\circ}\text{C}$  (at 50-200°C).

24. (Previously Presented) The adhesion-enhanced polyimide film according to claim 23, wherein the polyimide (A) is obtained from 3,3',4,4'-biphenyltetracarboxylic dianhydride and p-phenylenediamine or p-phenylenediamine and 4,4'-diaminodiphenyl ether, from 3,3',4,4'-biphenyltetracarboxylic dianhydride and pyromellitic dianhydride and p-phenylenediamine or p-phenylenediamine and 4,4'-diaminodiphenyl ether, or from pyromellitic dianhydride and p-phenylenediamine and 4,4'-diaminodiphenyl ether.

25. (Previously Presented) The adhesion-enhanced polyimide film according to claim 23, wherein the polyimide (A) is obtained using 3,3',4,4'-biphenyltetracarboxylic dianhydride and p-phenylenediamine as the main components at 50 mole percent or greater to 100 mole percent of the total.

26. (Cancelled)

27. (Previously Presented) The adhesion-enhanced polyimide film according to claim 23, wherein the polyimide (A) core layer has a thickness of 10 to 35  $\mu\text{m}$ .

28. (Currently Amended) An adhesion-enhanced polyimide film in which a metal layer is laminated ~~directly or~~ via an adhesive onto an adhesion-enhanced polyimide film according to claim 23.

29. (Currently Amended) A flexible metal foil laminated body comprising a metal layer laminated ~~directly or~~ via an adhesive onto an adhesion-enhanced polyimide film according to claim 23.

30. (Currently Amended) A flexible metal foil laminated body comprising a metal layer laminated ~~directly or~~ via an adhesive onto an adhesion-enhanced polyimide film according to claim 24.

31. (Currently Amended) A flexible metal foil laminated body comprising a metal layer laminated ~~directly or~~ via an adhesive onto an adhesion-enhanced polyimide film according to claim 25.

32. (Cancelled)

33. (Currently Amended) A flexible metal foil laminated body comprising a metal layer laminated ~~directly or~~ via an adhesive onto an adhesion-enhanced polyimide film according to claim 27.

34. (Cancelled)

35. (New) The adhesion-enhanced polyimide film according to claim 23, which is used to directly laminate the polyimide (B) layer onto an adhesive layer for adhesion to a metal layer.

36. (New) The adhesion-enhanced polyimide film according to claim 23, wherein the self-supporting film obtained from the polyimide precursor solution which yields the polyimide (A) core layer has a heat loss in a range of 20-40 wt% and an imidation rate in a range 8-40%.

37. (New) The adhesion-enhanced polyimide film according to claim 23, wherein the organic solvent solution comprising the polyimide precursor which yields a polyimide (B) thin layer is obtained by adding the heat-resistant surface treatment agent in a proportion of 1-15 wt% with respect to the polyimide precursor.

38. (New) A laminated body comprising an adhesive layer for adhesion to a metal layer formed onto the polyimide (B) layer of the adhesion enhanced polyimide film according to claim 23.